

12 Leads - DFN 4x4
Package Material Declaration

Date	28-Sep-20	Product name	Integrated Circuit
Package Code	LW	RoHS Compliant	Y
Package Name	Micro Leadframe Package Dual	Halogen Free	Y
Product Total Mass (g)	0.0438	Plating	electroplating+Sn immersion

Product Number MLX81115

Material Declaration

Part Name	Material Name	Component Weight (g)	Material Component (Element)	CAS #	Element ratio (%)	Material Weight (g)	Ratio total Wt (ppm)
Leadframe	Copper Alloy EFTEC64T (C18045)	0.0163	Copper (Cu)	7440-50-8	99.32	0.01621	370533
			Chromium (Cr)	7440-47-3	0.236	0.00004	880
			Tin (Sn)	7440-31-5	0.224	0.00004	836
			Zinc (Zn)	7440-66-6	0.186	0.00003	694
			Silicon (Si)	7440-21-3	0.012	0.000002	45
			others	-	0.022	0.000004	82
Leadframe Plating	Silver	0.00001	Silver (Ag)	7440-22-4	100	0.00001	261
Die	Silicon	0.0048	Silicon (Si)	7440-21-3	99.99	0.00482	110057
			others	-	0.01	0.0000005	11
Die attach material	Silver Adhesive 8600	0.0005	Silver (Ag)	7440-22-4	85	0.00040	9158
			Bismaleimide resin	-	15	0.00007	1616
Wire	Gold with Platinum	0.0001	Gold (Au)	7440-57-5	99.2	0.00010	2316
			Platinum (Pt)	7440-06-4	0.6	0.000001	14
			Palladium (Pd)	7440-05-3	0.2	0.0000002	5
Lead Finish	Tin	0.0012	Tin (Sn)	7440-31-5	99.99	0.00121	27733
			others	7439-92-1	0.01	0.0000001	3
Encapsulation	Epoxy resin EME G700LTD	0.0208	Silica	60676-86-0	85	0.01769	404393
			Silica	7631-86-9	5	0.00104	23788
			Epoxy Resin	-	5	0.00104	23788
			Phenol Resin	-	2.3	0.00048	10942
			Carbon Black	1333-86-4	0.4	0.00008	1903
			others	-	2.3	0.00048	10942

Total package weight (g) 0.0438

Comments

- Composition derived from MSDS and material CoC from vendors
- Component weight based on assembly of generic parts
- Reliability qualification reports are available upon request through the appropriate sales or marketing contact
- Third party testing for RoHS substances are available upon request to environment@melexis.com

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